



Specification for Approval

Customer: _____

Model Name: _____

Supplier Approval			Customer approval
R&D Designed	R&D Approved	QC Approved	
<i>Peter</i>	<i>Peng Jun</i>		

Revision Record

REV NO.	REV DATE	CONTENTS	Note
A	2019-06-26	NEW ISSUE	

Table of Contents

List	Description	Page No.
	Cover	1
	Revision Record	2
	Table of Contents	3
1	Scope	4
2	General Information	4
3	External Dimensions	5
4	Interface Description	6
5	Absolute Maximum Ratings	7
6	DC Characteristics	7
7	Timing Characteristics	8
8	Backlight Characteristics	14
9	Optical Characteristics	15
10	Reliability Test Conditions and Methods	17
11	Inspection Standard	18
12	Handling Precautions	22
13	Precaution for Use	23
14	Packing Method	23

1. Scope

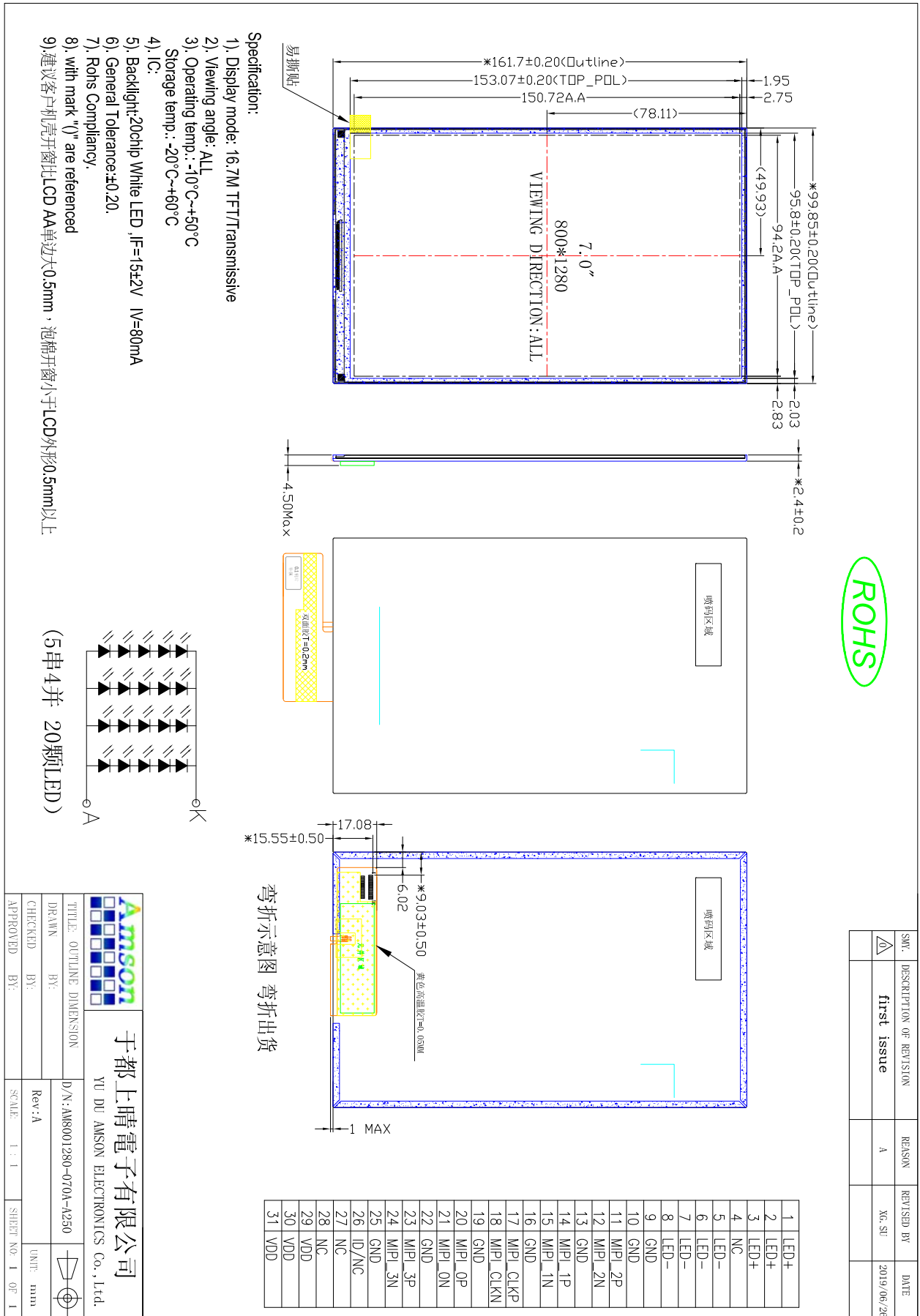
This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution.

2. General Information

ITEM	STANDARD VALUES	UNITS
Panel Size	7.0"	inch
Number of Pixels	800×RGB (3) ×1280	pixels
Active Area	94.2(H)x 150.72(V)	mm
Pixel Pitch	0.03925(H)×0.11775(V)	mm
Outline Dimension	99.85(W)×161.7(H)×2.4(D)	mm
Number of Colors	16.7M	-
Display Mode	Normally Black	-
Viewing Direction	ALL	-
Display Format	RGB vertical stripe	-
Luminance	320	nit
Contrast Ratio	850(TYP.)	
Surface Treatment	Hard coating	-
Interface	MIPI	-
Backlight	White LED	-
Operation Temperature	-10~50	°C
Storage Temperature	-20~60	°C
Polarizer Type	AG: Anti Glare(2H,3H)	-
	HC: Hard Coating	-

3. External Dimensions



于都上晴电子有限公司
YU DU AMSON ELECTRONICS Co., Ltd.

Amson

TITLE	OUTLINE DIMENSION
DRAWN BY:	
CHECKED BY:	
APPROVED BY:	
Rev: A	
SCALE: 1:1	
SHEET NO. 1 OF 1	

D/N: AM8001280-070A-A250

UNIT: mm

4. Interface Description

PIN NO.	PIN NAME	DESCRIPTION
1-3	LEDA	LED backlight (Anode).
4	NC	No connection
5~8	LEDK	LED backlight (Cathode).
9, 10	GND	Power ground
11	DSI_D2+	MIPI DSI differential data pair
12	DSI_D2-	MIPI DSI differential data pair
13	GND	Power ground
14	DSI_D1+	MIPI DSI differential data pair
15	DSI_D1-	MIPI DSI differential data pair
16	GND	Power ground
17	DSI_CLK+	MIPI DSI differential clock pair
18	DSI_CLK-	MIPI DSI differential clock pair
19	GND	Power ground
20	DSI_D0+	MIPI DSI differential data pair
21	DSI_D0-	MIPI DSI differential data pair
22	GND	Power ground
23	DSI_D3+	MIPI DSI differential data pair
24	DSI_D3-	MIPI DSI differential data pair
25	GND	Power ground
26	NC	NC
27	Reset	Reset chip
28	NC	No connection
29	IOVCC_1V8	Logic Supply Voltage
30, 31	VCC_3.3V	Analog Supply Voltage

5. Absolute Maximum Ratings

Parameter	Symbol	Spec.			Unit	Note
		Min.	Typ.	Max.		
I/O voltage	VDDIO_IF	1.8	-	3.6	V	
	VDDIO					
Power input	VDD	2.5	-	3.6	V	
VSP voltage	VSP	4.5	-	6	V	
VSN voltage	VSN	-4.5	-	-6	V	
VOTP power	VOTP	-	7.5	-	V	
Operating Temperature		-20	-	85	°C	(1)

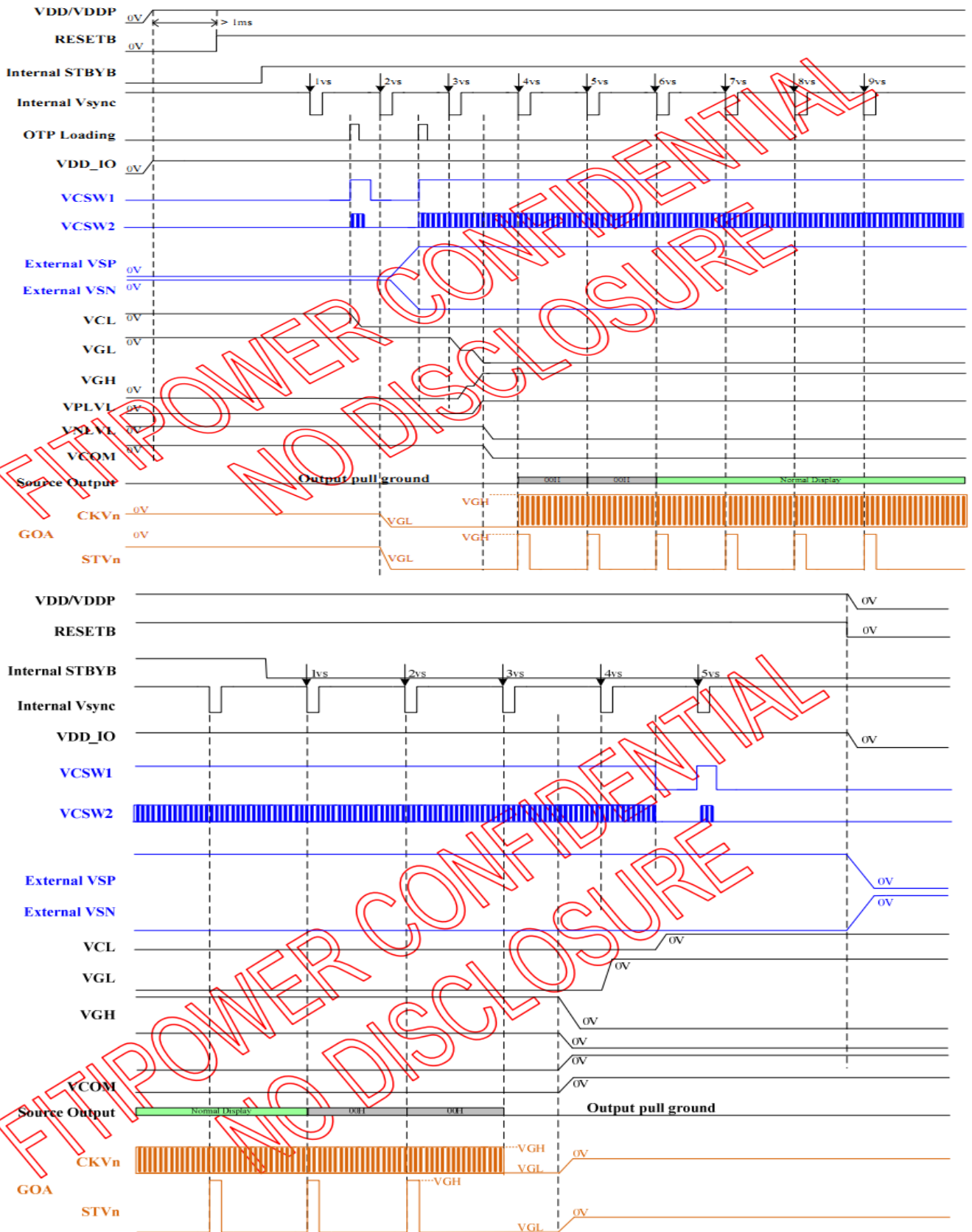
Note :(1) Do not let condensation for low temperature

6. DC Characteristics

Parameter	Symbol	Spec.			Unit	Note
		Min.	Typ.	Max.		
VDD voltage	VDD		3.3	-	V	Digital supply voltage
VDDP voltage	VDDP		5.3	-	V	Analog supply voltage
VDDIO voltage	VDDIO	-	3.3	-	V	I/O Power supply voltage
VOTP voltage	VOTP	-	7.5	-	V	Programming voltage
VSP voltage	VSP	4.5	5.0	6	V	VSP voltage
VSN voltage	VSN	-4.5	-5.0	-6	V	VSN voltage
VGH voltage	VGH	9.3	-	18	V	VGH voltage
VGL voltage	VGL	-16	-	-6.7	V	VGL voltage

7. Timing Characteristics

7.1. Power ON/OFF Sequence

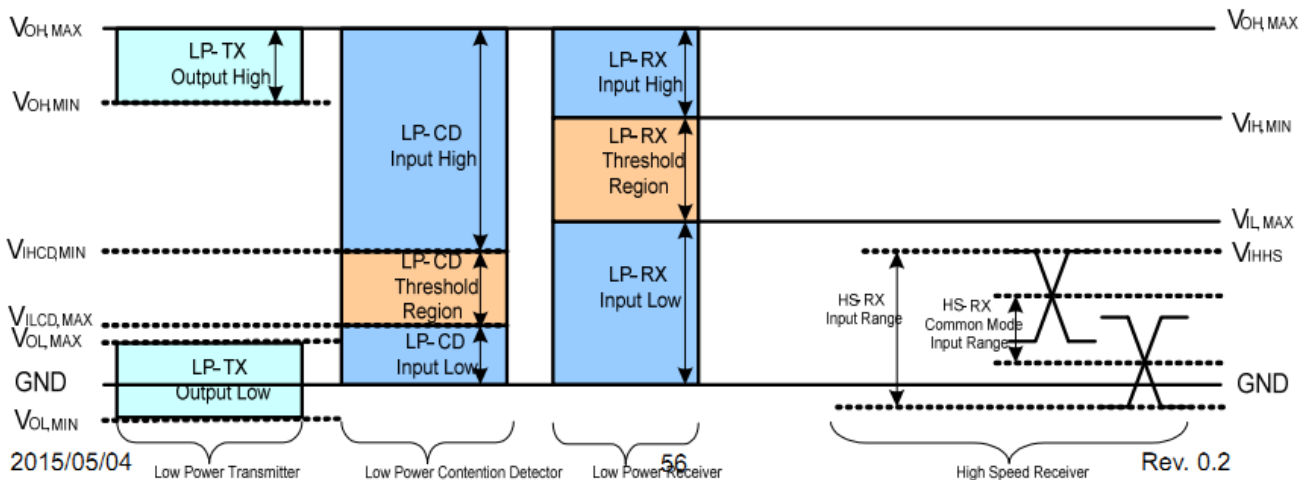


7.2 MIPI Characteristics

7.2.1 DC Specifications High-Speed Receiver Specification

(Test condition: VCI=1.6~3.6V, TA=-20°C ~ +85°C, VSS=VSSA=0V)

Parameter	Symbol	Spec.			Unit	Note
		Min.	Typ.	Max.		
VDDIO Input high level voltage	VIH	0.8 x VDDIO		VDDIO	V	
VDDIO input low level voltage	VIL	VSS		0.2 x VDDIO	V	
Input Leakage Current	Ileak	(-1)		(+1)	μA	
VGL_REG2 output voltage	VGL_REG2		TBD		V	
VGMP output voltage	VGMP		TBD		V	
VGMN output voltage	VGMN		TBD		V	
VCI1 output voltage	VCI1		TBD		V	
VGL output voltage	VGL_O	-16		-6	V	
VGH output voltage	VGH_O	8		19	V	
VCL output voltage	VCL	-2.1	-2.4	-3	V	
VOM output voltage	VCOM	-2.75	-1.48	-0.2	V	
Input terminal resistance	ZID		100		ohm	
Source output level deviation	Graycode = 0 ~ 14		TBD		mV	
	Graycode = 241 ~ 255		TBD		mV	
	Graycode = 15 ~ 31		TBD		mV	
	Graycode = 208 ~ 240		TBD		mV	
Source output offset deviation	Graycode = 32 ~ 207		TBD		mV	
	Graycode = 0 ~ 14	-	TBD		mV	
	Graycode = 241 ~ 255	-	TBD		mV	
	Graycode = 15 ~ 31	-	TBD		mV	
Source output offset deviation	Graycode = 208 ~ 240	-	TBD		mV	
	Graycode = 32 ~ 207	-	TBD		mV	
	Graycode = 0 ~ 14	-	TBD		mV	
Current consumption	Analog Operating	IAOP	TBD		mA	
	Analog Stand-by	IAST	TBD		mA	
Rush current	Ivddpeak		TBD		mA	
VOTP operation current	Ivpp		TBD		mA	



7.2.2 MIPI AC characteristics

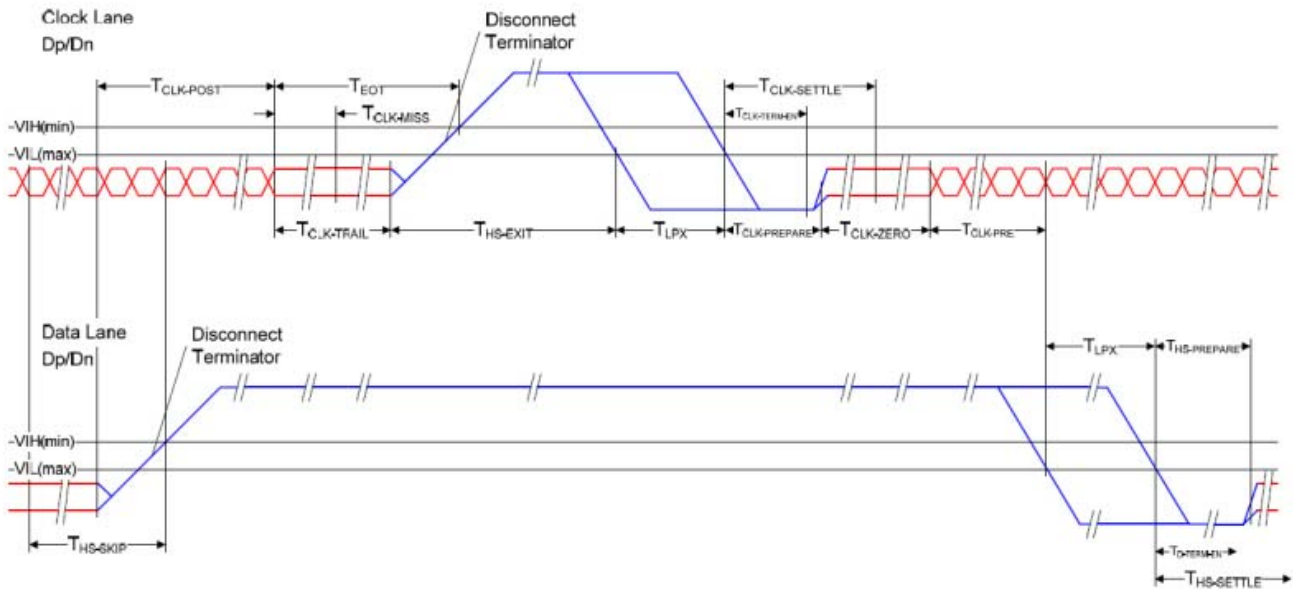


Figure 13.1: Switching the clock lane between clock transmission and low-power mode

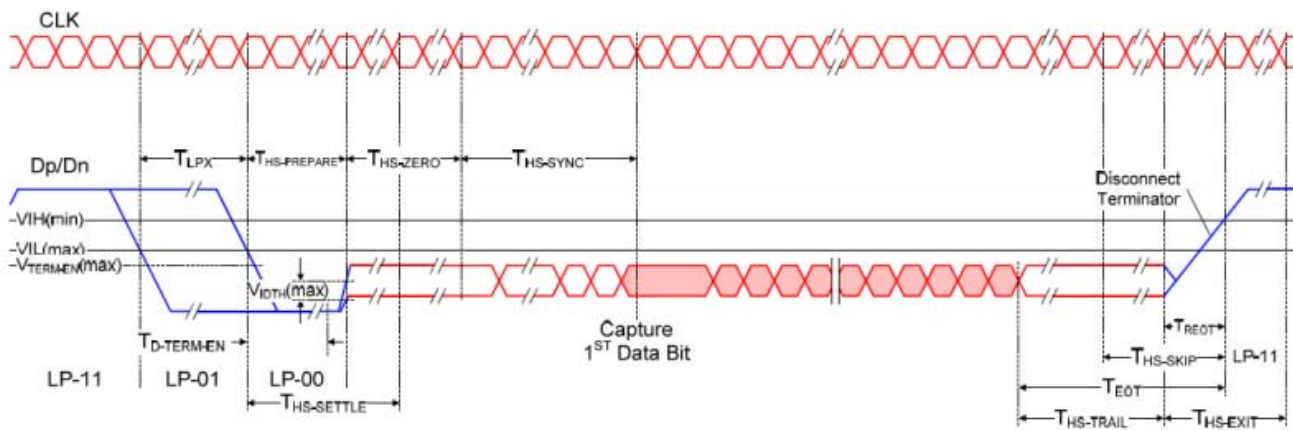


Figure 13.2: Timing of high-speed data transmission in bursts

7.3 MIPI data-clock timing specification

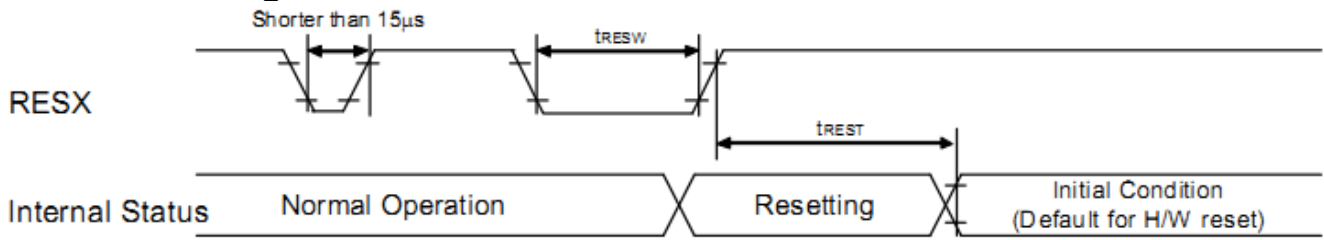
Parameter	Descript	Spec.			Unit
		Min.	Typ.	Max.	
T_{REOT}	30%-85% rise time and fall time	-	-	35	ns
$T_{CLK-MISS}$	Timeout for receiver to detect absence of Clock transitions and disable the Clock Lane HS-RX.	-	-	60	ns
$T_{CLK-POST}^{*1}$	Time that the transmitter continues to send HS clock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of $T_{HS-TRAIL}$ to the beginning of $T_{CLK-TRAIL}$.	$60\text{ ns} + 52 \cdot UI$ (For DCS)	-		ns
$T_{CLK-PRE}$	Time that the HS clock shall be driven by the transmitter prior to any associated Data Lane beginning the transition from LP to HS mode.	8	-		ns
$T_{CLK-SETTLE}$	Time interval during which the HS receiver shall ignore any Clock Lane HS transitions, starting from the beginning of $T_{CLK-PRE}$.	95	-	300	ns
$T_{CLK-TERM-EN}$	Time for the Clock Lane receiver to enable the HS line termination, starting from the time point when Dn crosses $V_{IL,MAX}$.		-	38	ns
$T_{HS-SETTLE}$	Time interval during which the HS receiver shall ignore any Data Lane HS transitions, starting from the beginning of $T_{HS-PREPARE}$.	$85\text{ ns} + 6 \cdot UI$	-	$145\text{ ns} + 10 \cdot UI$	ns
T_{EOT}	Time from start of $T_{HS-TRAIL}$ or $T_{CLK-TRAIL}$ period to start of LP-11 state	-	-	$105\text{ns} + 48 \cdot UI$	-
$T_{HS-EXIT}^{(1)}$	time to drive LP-11 after HS burst	100	-	-	ns
$T_{HS-PREPARE}$	Time to drive LP-00 to prepare for HS transmission	$40\text{ns} + 4 \cdot UI$	-	$85\text{ns} + 6 \cdot UI$	ns
$T_{HS-PREPARE} + T_{HS-ZERO}$	$T_{HS-PREPARE}$ + Time to drive HS-0 before the Sync sequence	$145\text{ns} + 10 \cdot UI$	-	-	ns
$T_{HS-SKIP}$	Time-out at RX to ignore transition period of EoT	40	-	$55\text{ns} + 4 \cdot UI$	ns
$T_{HS-TRAIL}$	Time to drive flipped differential state after last payload data bit of a HS transmission burst	$60 + 4 \cdot UI$	-	-	ns
T_{LPX}	Length of any Low-Power state period	50	-	-	ns
Ratio T_{LPX}	Ratio of $T_{LPX(MASTER)}/T_{LPX(SLAVE)}$ between Master and Slave side	2/3	-	3/2	-
T_{TA-GET}	Time to drive LP-00 by new TX	$5 \cdot T_{LPX}$			ns
T_{TA-GO}	Time to drive LP-00 after Turnaround Request	$4 \cdot T_{LPX}$			ns
$T_{TA-SURE}$	Time-out before new TX side starts driving	T_{LPX}	-	$2 \cdot T_{LPX}$	ns

Note: (1) For image transmission:

$T_{CLK-POST}$ min value = 164 when MIPI max frequency per lane = 0.53Gbps.

$T_{CLK-POST}$ min value = 112 when MIPI max frequency per lane = 1Gbps

7.4. Reset Timing Characteristics



Reset timing:

IOVCC=1.65V to 3.6V, AGND=DGND=0V, Ta=-40 to 85°C

Symbol	Parameter	Related Pins	MIN	TYP	MAX	Note	Unit
t_{RESW}	*1) Reset low pulse width	RESX	15	-	-		μs
t_{REST}	*2) Reset complete time	-	-	-	5	When reset applied during sleep-in mode	ms
		-	-	-	120	When reset applied during sleep-out mode	ms

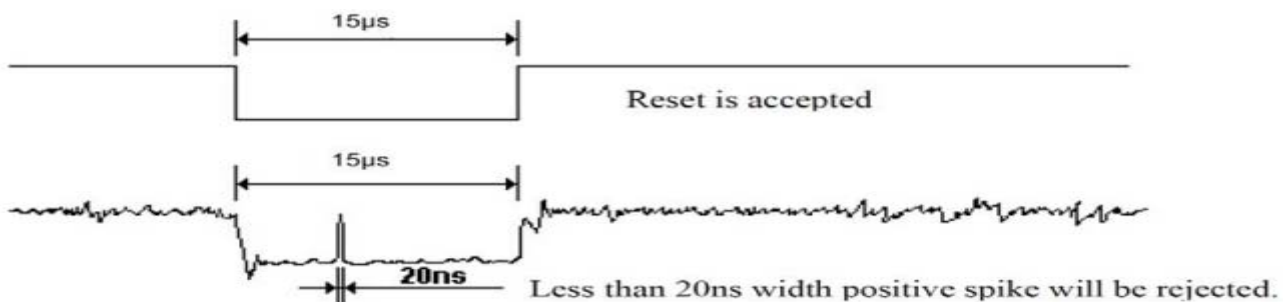
RESX Pulse	Action
Shorter than 5 μs	Reset Rejected
Longer than 15 μs	IC Reset
Between 5 μs and 15 μs	Reset starts (It depends on voltage and temperature condition.)

Note 1) Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below.

Note 2. During the resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode) and then return to Default condition for H/W reset.

Note 3. During Reset Complete Time, data in MTP will be latched to internal register during this period. This loading is done every time when there is H/W reset complete time (t_{REST}) within 5ms after a rising edge of RESX.

Note 4. Spike Rejection also applies during a valid reset pulse as shown below:



Note 5. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

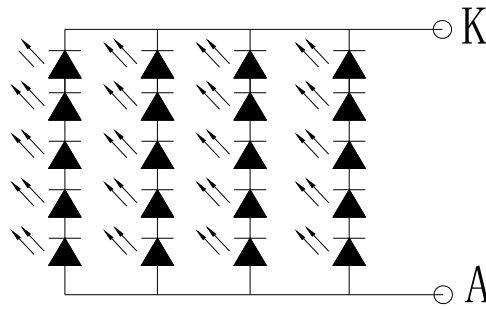
7.5 Input Timing table

For 800RGBx1280

Parameter	Symbol	Value			Unit
		Min.	Typ.	Max.	
MIPI (4 Lane) @Frame rate=60Hz			432		Mbps
MIPI (3 Lane) @Frame rate=60Hz			576		Mbps
DCLK frequency @Frame rate=60Hz	F _{DCLK}		71.9		MHz
HSYNC period time	T _H		920		DCLK
Horizontal display area	T _{HD}		800		DCLK
HSYNC pulse width	T _{HPW}		24	-	DCLK
HSYNC back porch	T _{HBP}		24	-	DCLK
HSYNC front porch	T _{HFP}		72	-	DCLK
VSYNC period time	T _V		1304		H
Vertical display area	T _{VD}		1280		H
VSYNC pulse width	T _{VPW}		2	-	H
VSYNC back porch	T _{VBP}		10	-	H
VSYNC front porch	T _{VFP}		12	-	H

MIPI Frequency = (Frame rate) x T_H x T_V x 24bits.

8. Backlight Characteristic



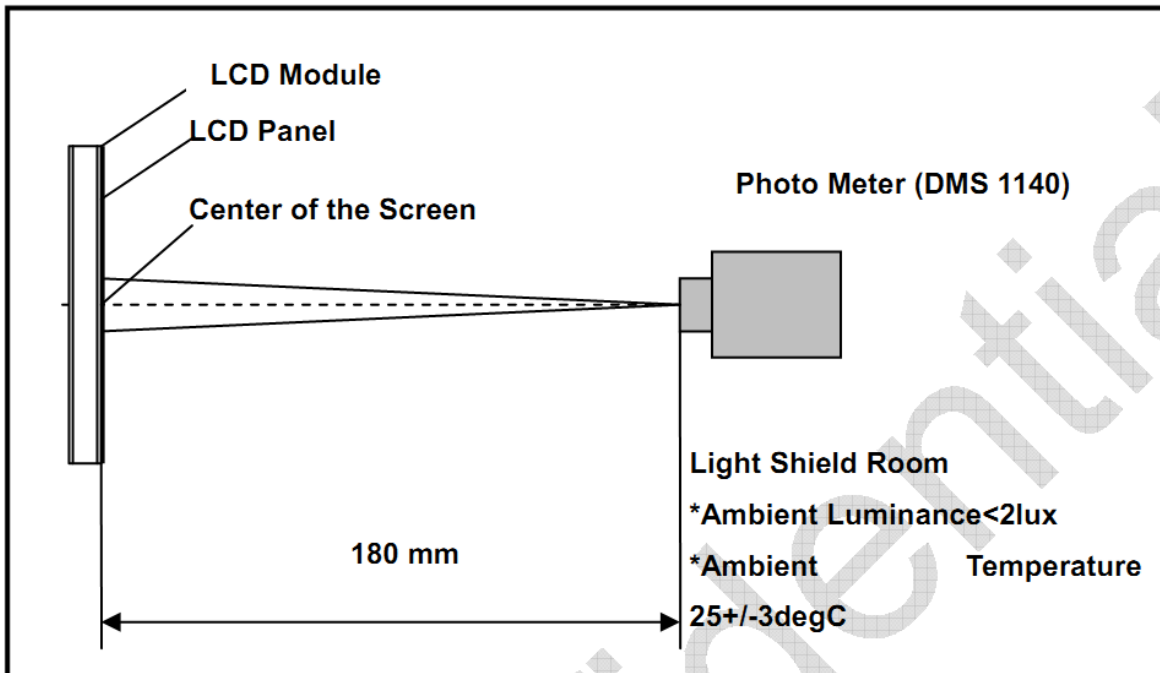
(5串4并 20颗LED)

Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	22	24	25	V	If=60mA
Supply Current	If	-	40	-	mA	
Luminous Intensity for LCM	-	200	250	-	cd/m ²	If=60mA
Uniformity for LCM	-	80	-	-	%	If=60mA
Life Time	-	0	20000	-	Hr	If=60mA
Backlight Color	White					

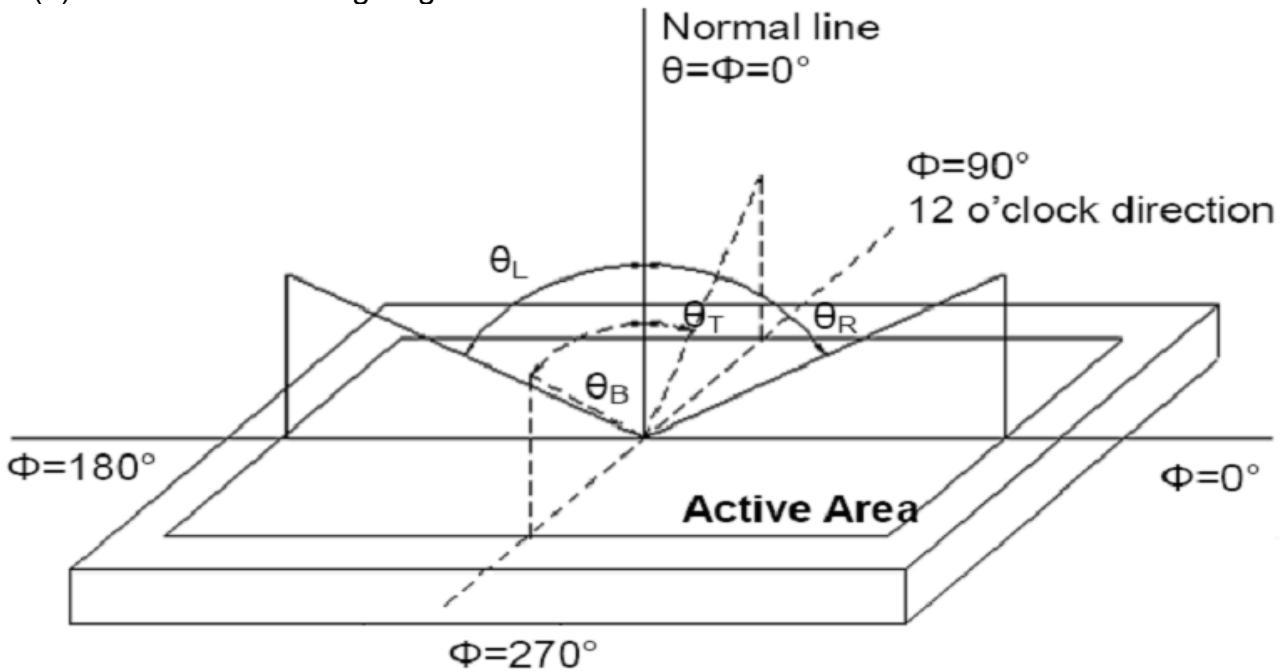
9. Optical Characteristics

Item	Conditions	Min.	Typ.	Max.	Unit	Note	
Viewing Angle (CR>10)	Horizontal	θ_L	-	80	-	degree	(1),(2),(6)
		θ_R	-	80	-		
	Vertical	θ_T	-	80	-		
		θ_B	-	80	-		
Contrast Ratio	Center	600	800	-	-	(1),(3),(6)	
Response Time	Rising	-	25	-	ms	(1),(4),(6)	
	Falling						
CF Color Chromaticity (CIE1931)	Red x	Typ. -0.05	TBD	Typ. +0.05	-	(1), (6)	
	Red y		TBD		-		
	Green x		TBD		-		
	Green y		TBD		-		
	Blue x		TBD		-		
	Blue y		TBD		-		
	White x		TBD		-		
	White y		TBD		-		

Note (1) Measurement Setup: The LCD module should be stabilized at given temp. 25°C for 15 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 15 minutes in a windless room.



Note (2) Definition of Viewing Angle



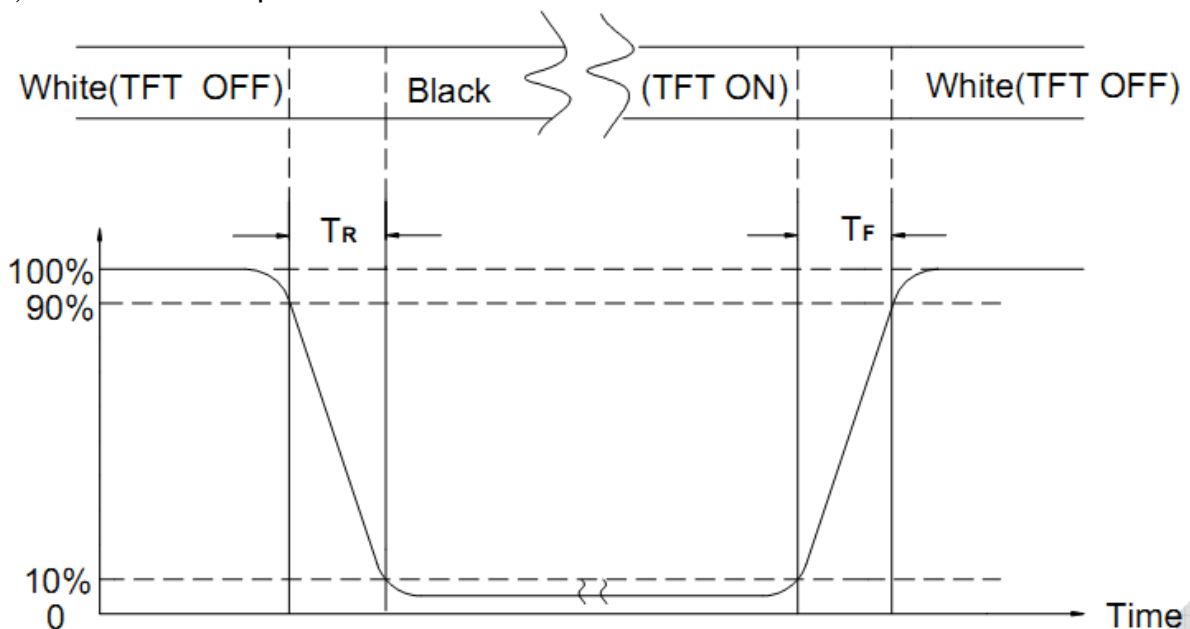
Note (3) Definition of Contrast Ratio (CR)

The contrast ratio can be calculated by the following expression

$$\text{Contrast Ratio (CR)} = L63 / L0$$

L63: Luminance of gray level 63, L0: Luminance of gray level 0

Note (4) Definition of response time



Note (5) Definition of Transmittance (Module is without signal input)

$$\text{Transmittance} = \text{Center Luminance of LCD} / \text{Center Luminance of Back Light} \times 100\%$$

Note (6) Definition of color chromaticity (CIE1931)

Color coordinates measured at the center point of LCD

10. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
①	High Temperature Storage	80°C±2°C×96Hours	Inspection after 2~4hours storage at room temperature, the samples should be free from defects: 1, Air bubble in the LCD. 2, Seal leak. 3, Non-display. 4, Missing segments. 5, Glass crack. 6, Current IDD is twice higher than initial value. 7, The surface shall be free from damage. 8, The electric characteristic requirements shall be satisfied.
②	Low Temperature Storage	-30°C±2°C×96Hours	
③	High Temperature Operating	70°C±2°C×96Hours	
④	Low Temperature Operating	-20°C±2°C×96Hours	
⑤	Temperature Cycle(Storage)	-20°C ↔ 25°C ↔ 70°C (30min) ← (5min) → (30min) 1cycle Total 10cycle	
⑥	Damp Proof Test (Storage)	50°C±5°C×90%RH×96Hours	
⑦	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5MM X,Y,Z direction for total 3hours (packing condition test will be tested by a carton)	
⑧	Drooping Test	Drop to the ground from 1M height one time every side of carton. (packing condition test will be tested by a carton)	
⑨	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

REMARK:

- 1, The Test samples should be applied to only one test item.
- 2, Sample side for each test item is 5~10pcs.
- 3, For Damp Proof Test, Pure water(Resistance > 10MΩ) should be used.
- 4, In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
- 5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
- 6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

11. Inspection Standard

11.1. QUALITY :

THE QUALITY OF GOODS SUPPLIED TO PURCHASER SHALL COME UP TO THE FOLLOWING STANDARD.

11.1.1. THE METHOD OF PRESERVING GOODS

AFTER DELIVERY OF GOODS FROM AMSON TO PURCHASER. PURCHASER SHALL CONTROL THE LCM AT -10 °C TO 40°C ,AND IT MIGHT BE DESIRABLE TO KEEP AT THE NORMAL ROOM TEMPERATURE AND HUMIDITY UNTIL INCOMING INSPECTION OR THROWING INTO PROCESS LINE.

11.1.2. INCOMING INSPECTION

(A) THE METHOD OF INSPECTION

IF PURCHASER MAKE AN INCOMING INSPECTION , A SAMPLING PLAN SHALL BE APPLIED ON THE CONDITION THAT QUALITY OF ONE DELIVERY SHALL BE REGARDED AS ONE LOT.

(B) THE STANDARD OF QUALITY

ISO-2859-1 (SAME AS MIL-STD-105E) , LEVEL II SINGLE PLAN.

CLASS	AQL(%)
CRITICAL	0.4 %
MAJOR	0.65 %
MINOR	1.5 %
TOTAL	1.5 %

EVERY ITEM SHALL BE INSPECTED ACCORDING TO THE CLASS.

(C) MEASURE

IF AS THE RESULT OF ABOVE RECEIVING INSPECTION , A LOT OUT IS DISCOVERED. PURCHASER SHALL BE INFORM SELLER OF IT WITHIN SEVEN DAYS. BUT FIRST SHIPMENT WITHIN FOURTEEN DAYS.

11.1.3. WARRANTY POLICY

AMSON WILL PROVIDE ONE-YEAR WARRANTY FOR THE PRODUCTS ONLY IF UNDER SPECIFICATION OPERATING CONDITIONS. AMSON WILL REPLACE NEW PRODUCTS FOR THESE DEFECT PRODUCTS WHICH UNDER WARRANTY PERIOD AND BELONG TO THE RESPONSIBILITY OF AMSON.

11.2. CHECKING CONDITION

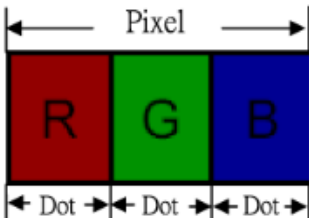
11.2.1. CHECKING DIRECTION SHALL BE IN THE 45 DEGREE AREA TO FACE THE SAMPLE.

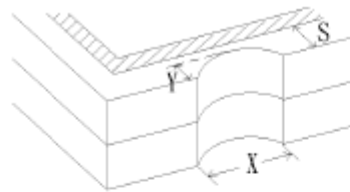
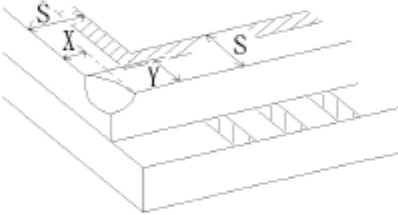
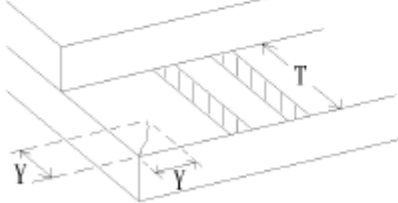
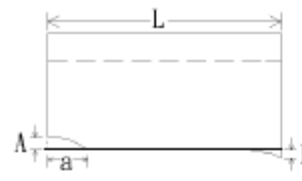
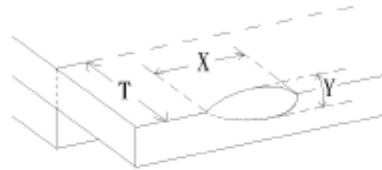
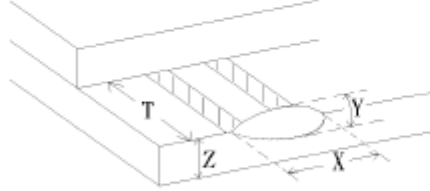
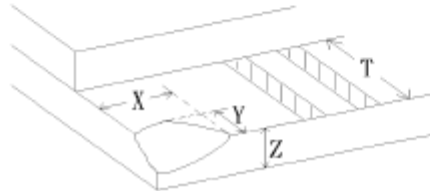
11.2.2. CHECKER SHALL SEE OVER 300±25 mm. WITH BARE EYES FAR FROM SAMPLE AND USING 2 PCS. OF 20W FLUORESCENT LAMP.

11.3. INSPECTION PLAN :

CLASS	ITEM	JUDGEMENT	CLASS
PACKING & INDICATE	1. OUTSIDE AND INSIDE PACKAGE	"MODEL NO." , "LOT NO." AND "QUANTITY" SHOULD INDICATE ON THE PACKAGE.	Minor
	2. MODEL MIXED AND QUANTITY	OTHER MODEL MIXED.....REJECTED QUANTITY SHORT OR OVER.....REJECTED	Critical
	3. PRODUCT INDICATION	"MODEL NO." SHOULD INDICATE ON THE PRODUCT	Major
ASSEMBLY	4. DIMENSION, LCD GLASS SCRATCH AND SCRIBE DEFECT.	ACCORDING TO SPECIFICATION OR DRAWING.	Major
APPEARANCE	5. VIEWING AREA	POLARIZER EDGE OR LCD'S SEALING LINE IS VISABLE IN THE VIEWING AREAREJECTED	Minor
	6. BLEMISH · BLACK SPOT · WHITE SPOT IN THE LCD AND LCD GLASS CRACKS	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	7. BLEMISH · BLACK SPOT WHITE SPOT AND SCRATCH ON THE POLARIZER	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	8. BUBBLE IN POLARIZER	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	9. LCD'S RAINBOW COLOR	STRONG DEVIATION COLOR (OR NEWTON RING) OF LCD.....REJECTED. OR ACCORDING TO LIMITED SAMPLE (IF NEEDED, AND INSIDE VIEWING AREA)	Minor
ELECTRICAL	10. ELECTRICAL AND OPTICAL CHARACTERISTICS (CONTRAST· VOP · CHROMATICITY ... ETC)	ACCORDING TO SPECIFICATION OR DRAWING . (INSIDE VIEWING AREA)	Critical
	11.MISSING LINE	MISSING DOT · LINE · CHARACTERREJECTED	Critical
	12.SHORT CIRCUIT· WRONG PATTERN DISPLAY	NO DISPLAY · WRONG PATTERN DISPLAY · CURRENT CONSUMPTION OUT OF SPECIFICATION..... REJECTED	Critical
	13. DOT DEFECT (FOR COLOR AND TFT)	ACCORDING TO STANDARD OF VISUAL INSPECTION	Minor

11.4. STANDARD OF VISUAL INSPECTION

NO.	CLASS	ITEM	JUDGEMENT																				
11.4.1	MINOR	BLACK AND WHITE SPOT FOREIGN MATERIEL DUST IN THE CELL BLEMISH SCRATCH	<p>(A) ROUND TYPE: unit : mm.</p> <table border="1"> <thead> <tr> <th>DIAMETER (mm.)</th> <th>ACCEPTABLE Q'TY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.1$</td> <td>DISREGARD</td> </tr> <tr> <td>$0.1 < \Phi \leq 0.25$</td> <td>3 (Distance>5mm)</td> </tr> <tr> <td>$0.25 < \Phi$</td> <td>0</td> </tr> </tbody> </table> <p>NOTE: $\Phi = (\text{LENGTH} + \text{WIDTH}) / 2$</p> <p>(B) LINEAR TYPE: unit : mm.</p> <table border="1"> <thead> <tr> <th>LENGTH</th> <th>WIDTH</th> <th>ACCEPTABLE Q'TY</th> </tr> </thead> <tbody> <tr> <td>-----</td> <td>$W \leq 0.03$</td> <td>DISREGARD</td> </tr> <tr> <td>$L \leq 5.0$</td> <td>$0.03 < W \leq 0.07$</td> <td>3 (Distance>5mm)</td> </tr> <tr> <td>-----</td> <td>$0.07 < W$</td> <td>FOLLOW ROUND TYPE</td> </tr> </tbody> </table>	DIAMETER (mm.)	ACCEPTABLE Q'TY	$\Phi \leq 0.1$	DISREGARD	$0.1 < \Phi \leq 0.25$	3 (Distance>5mm)	$0.25 < \Phi$	0	LENGTH	WIDTH	ACCEPTABLE Q'TY	-----	$W \leq 0.03$	DISREGARD	$L \leq 5.0$	$0.03 < W \leq 0.07$	3 (Distance>5mm)	-----	$0.07 < W$	FOLLOW ROUND TYPE
DIAMETER (mm.)	ACCEPTABLE Q'TY																						
$\Phi \leq 0.1$	DISREGARD																						
$0.1 < \Phi \leq 0.25$	3 (Distance>5mm)																						
$0.25 < \Phi$	0																						
LENGTH	WIDTH	ACCEPTABLE Q'TY																					
-----	$W \leq 0.03$	DISREGARD																					
$L \leq 5.0$	$0.03 < W \leq 0.07$	3 (Distance>5mm)																					
-----	$0.07 < W$	FOLLOW ROUND TYPE																					
11.4.2	MINOR	BUBBLE IN POLARIZER DENT ON POLARIZER	<p style="text-align: right;">unit : mm.</p> <table border="1"> <thead> <tr> <th>DIAMETER</th> <th>ACCEPTABLE Q'TY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.2$</td> <td>DISREGARD</td> </tr> <tr> <td>$0.2 < \Phi \leq 0.5$</td> <td>2 (Distance>5mm)</td> </tr> <tr> <td>$0.5 < \Phi$</td> <td>0</td> </tr> </tbody> </table>	DIAMETER	ACCEPTABLE Q'TY	$\Phi \leq 0.2$	DISREGARD	$0.2 < \Phi \leq 0.5$	2 (Distance>5mm)	$0.5 < \Phi$	0												
DIAMETER	ACCEPTABLE Q'TY																						
$\Phi \leq 0.2$	DISREGARD																						
$0.2 < \Phi \leq 0.5$	2 (Distance>5mm)																						
$0.5 < \Phi$	0																						
11.4.3	MINOR	Dot Defect	<table border="1"> <thead> <tr> <th>Items</th> <th>ACC. Q'TY</th> </tr> </thead> <tbody> <tr> <td>Bright dot</td> <td>$N \leq 4$</td> </tr> <tr> <td>Dark dot</td> <td>$N \leq 4$</td> </tr> </tbody> </table> <p>Pixel Define :</p>  <p>Note 1: The definition of dot: The size of a defective dot over 1/2 of whole dot is regarded as one defective dot. Note 2: Bright dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern. Note 3: Dark dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue pattern.</p>	Items	ACC. Q'TY	Bright dot	$N \leq 4$	Dark dot	$N \leq 4$														
Items	ACC. Q'TY																						
Bright dot	$N \leq 4$																						
Dark dot	$N \leq 4$																						

NO.	CLASS	ITEM	JUDGEMENT
11.4.4	MINOR	LCD GLASS CHIPPING	 $Y > S$ Reject
11.4.5	MINOR	LCD GLASS CHIPPING	 $X \text{ or } Y > S$ Reject
11.4.6	MAJOR	LCD GLASS GLASS CRACK	 $Y > (1/2) T$ Reject
11.4.7	MAJOR	LCD GLASS SCRIBE DEFECT	 <ol style="list-style-type: none"> $a > L/3$, $A > 1.5\text{mm}$. Reject B : ACCORDING TO DIMENSION
11.4.8	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL AREA)	 $\Phi = (x+y)/2 > 2.5 \text{ mm}$ Reject
11.4.9	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL SURFACE)	 $Y > (1/3) T$ Reject
11.4.10	MINOR	LCD GLASS CHIPPING	 $Y > T$ Reject

12. Handling Precautions

12.1. Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizers which easily be damaged. And since the module is so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2. Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns

Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (Cl) , Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happens by miss-handling or using some materials such as Chlorine (Cl), Sulfur (S) from customer, Responsibility is on customer.

12.3. Caution against static charge

The LCD module uses C-MOS LSI drivers, so we recommend that you:

Connect any unused input terminal to power or ground, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4. packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5. Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage than the limit causes the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the maximum operating temperature, 50%Rh or less is required.

12.6. storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
[It is recommended to store them as they have been contained in the inner container at the time of delivery from us.]

12.7. Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

13. Precaution for Use

13.1.

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2.

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification.
- When a new problem is arisen this is not specified in this specification.
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT and some problem is arisen in this specification due to the change.
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method

TBD